

L Number	Hits	Search Text	DB	Time stamp
-	427	(432/253).CCLS.	USPAT	2004/01/08 14:56
-	169	(wafer or substrate) and ((432/253).CCLS.)	USPAT	2004/01/08 15:14
-	223	(432/258).CCLS.	USPAT	2004/01/08 15:14
-	74	(wafer or substrate) and ((432/258).CCLS.)	USPAT	2004/01/08 15:25
-	34	((wafer or substrate) and ((432/258).CCLS.)) not ((wafer or substrate) and ((432/253).CCLS.))	USPAT	2004/01/08 15:24
-	776	((392/416) or (392/418)).CCLS.	USPAT	2004/01/08 15:25
-	411	(wafer or substrate) and (((392/416) or (392/418)).CCLS.)	USPAT	2004/01/08 16:16
-	394	((wafer or substrate) and (((392/416) or (392/418)).CCLS.)) not (((wafer or substrate) and ((432/258).CCLS.)) not (wafer or substrate) and ((432/253).CCLS.)) or ((wafer or substrate) and ((432/253).CCLS.))	USPAT	2004/01/08 16:15
-	314	(432/247).CCLS.	USPAT	2004/01/08 16:17
-	20	(wafer or substrate) and ((432/247).CCLS.)	USPAT	2004/01/08 16:17
-	102	(432/237).CCLS.	USPAT	2004/01/08 16:17
-	3	(wafer or substrate) and ((432/237).CCLS.)	USPAT	2004/01/08 16:18
-	388	(432/250).CCLS.	USPAT	2004/01/08 16:18
-	23	(wafer or substrate) and ((432/250).CCLS.)	USPAT	2004/01/08 16:21
-	75	(219/443.1).CCLS.	USPAT	2004/01/08 16:22
-	10	(wafer or substrate) and ((219/443.1).CCLS.)	USPAT	2004/01/08 16:22
-	120	(219/444.1).CCLS.	USPAT	2004/01/08 16:22
-	112	(wafer or substrate) and ((219/444.1).CCLS.)	USPAT	2004/01/08 16:32
-	952	(heat\$3 NEAR4 platen) and (wafer or substrate) and upper and lower	USPAT	2004/01/08 16:33
-	267	semiconductor and ((heat\$3 NEAR4 platen) and (wafer or substrate) and upper and lower)	USPAT	2004/01/08 16:34
-	38	lid and (semiconductor and ((heat\$3 NEAR4 platen) and (wafer or substrate) and upper and lower))	USPAT	2004/01/09 07:22
-	2285	(lid or cover).ab. and (wafer or semiconductor) and thermal	USPAT	2004/01/09 07:23
-	362	lid.ab. and (wafer or semiconductor) and thermal	USPAT	2004/01/09 07:23